



General Description

The AOZ1117 is a low dropout positive adjustable or fixed-mode regulator with minimum of 1A output current capability. The product is specifically designed to provide well-regulated supply for low voltage IC applications such as high-speed bus termination and low current 3.3V logic supply. The AOZ1117 is also well suited for other applications such as VGA cards. The AOZ1117 is guaranteed to have lower than 1.4V dropout at full load current making it ideal to provide well-regulated outputs of 1.25V to 5.0V with 2.75V to 14V input supply.

Features

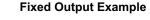
- 1.4V maximum dropout at full load current
- Fast transient response
- Output current limiting
- Built-in thermal shutdown
- Good noise rejection
- 3-terminal adjustable or fixed 1.5V, 1.8V, 2.5V, 3.3V, or 5.0V
- TO252 package

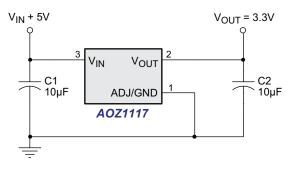
Applications

- PC peripheral
- Communication



Typical Circuits





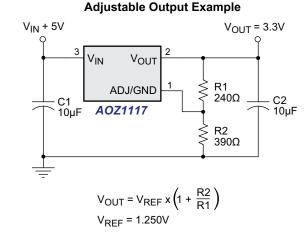


Figure 1.

Ordering Information

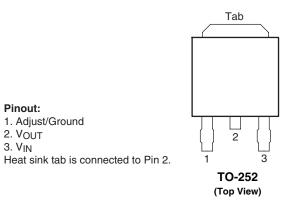
| Part Number | Output Voltage | Ambient Temperature Range | Package | Environmental | | | |
|---------------|----------------|------------------------------|---------|---------------|--|--|--|
| AOZ1117TI-AAL | Adjustable | able | | | | | |
| AOZ1117TI-15L | 1.5V | | | | | | |
| AOZ1117TI-18L | 1.8V | -40°C to +85°C | TO-252 | Green Product | | | |
| AOZ1117TI-25L | 2.5V | -40 C 10 +65 C | 10-252 | Green Floduct | | | |
| AOZ1117TI-33L | 3.3V | | | | | | |
| AOZ1117TI-50L | 5.0V | | | | | | |

• All AOS products are offered in packages with Pb-free plating and compliant to RoHS standards.

• Parts marked as Green Products (with "L" suffix) use reduced levels of Halogens, and are also RoHS compliant.

Please visit www.aosmd.com/web/quality/rohs_compliant.jsp for additional information.

Pin Configuration



Pin Description

| Name | I/O | Pin # | Function |
|-----------|-----|-------|---|
| Adj (GND) | I | 1 | A resistor divider from this pin to the Vout pin and ground sets the output voltage. (Ground only for Fixed-Mode) |
| Vout | 0 | 2 | The output of the regulator. A minimum of 10uF capacitor ($0.15\Omega \le ESR \le 20\Omega$) must be connected from this pin to ground to insure stability. |
| Vin | Ι | 3 | The input pin of regulator. Typically a large storage capacitor $(0.15\Omega \le \text{ESR} \le 20\Omega)$ is connected from this pin to ground to insure that the input voltage does not sag below the minimum dropout voltage during the load transient response. This pin must always be 1.4V higher than Vout in order for the device to regulate properly. |



Absolute Maximum Ratings

Exceeding the Absolute Maximum ratings may damage the device.

| Parameter | Rating |
|--|-----------------|
| V _{IN} to GND | -0.3V to +15V |
| Maximum Junction Temperature (T _J) | 150°C |
| Power Dissipation (P _D), T _A = 25°C, T _J = 125°C, P _D = (T _J - T _A) / θ J _A | |
| No heat sink; no air flow | 1050mW |
| Multi-layer PCB copper area (10mm x 10mm) | 1818mW |
| Storage Temperature (T _S) | -65°C to +150°C |
| ESD Rating ⁽¹⁾ | ±2kV |

Note:

1. Devices are inherently ESD sensitive, handling precautions are required. Human body model rating: 1.5k Ω in series with 100pF.

Recommend Operating Ratings

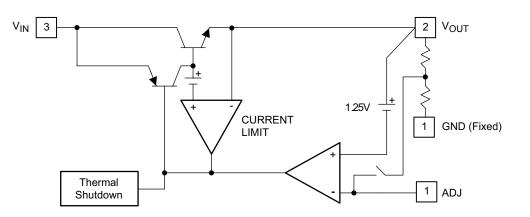
The device is not guaranteed to operate beyond the Maximum Operating Ratings.

| Parameter | Rating |
|--|----------------|
| Supply Voltage (V _{IN}) | 2.75V to +14V |
| Operating Junction Temperature (T _J) | 0°C to +125°C |
| Ambient Temperature (T _A) | -40°C to +85°C |
| Package Thermal Resistance $(\Theta_{JA})^{(2)}$ | 50°C/W |

Note:

2.The package Θ_{JA} is measured with the device mounted on 1-in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}$ C. The value in any given application depends on the user's specific board design.

Block Diagram



Electrical Characteristics

Under Operating Conditions

| Parameter | Device | Conditions | Min. | Тур. | Max | Unit |
|---|-------------|---|-------|-------|-------|------|
| Operation Input Voltage | All | | 2.75 | | 14 | V |
| Reference Voltage | AOZ1117-ADJ | $T_J = 25^{\circ}C, (V_{IN-OUT}) = 1.5V, I_{OUT} = 10mA$ | 1.225 | 1.250 | 1.275 | V |
| Output Voltage | AOZ1117-1.5 | $I_{OUT} = 10 \text{mA}, T_J = 25^\circ\text{C}, 3\text{V} \leq \text{V}_{IN} \leq 12\text{V}$ | 1.470 | 1.500 | 1.530 | V |
| | AOZ1117-1.8 | $I_{OUT} = 10 \text{mA}, T_J = 25^\circ\text{C}, 3.3 \text{V} \leq \text{V}_{\text{IN}} \leq 12 \text{V}$ | 1.764 | 1.800 | 1.836 | V |
| | AOZ1117-2.5 | $I_{OUT} = 10 \text{mA}, \text{T}_{\text{J}} = 25^{\circ}\text{C}, 4\text{V} \leq \text{V}_{\text{IN}} \leq 12\text{V}$ | 2.450 | 2.500 | 2.550 | V |
| | AOZ1117-3.3 | $I_{OUT} = 10 \text{mA}, \text{T}_{J} = 25^{\circ}\text{C}, 4.8\text{V} \leq \text{V}_{IN} \leq 12\text{V}$ | 3.235 | 3.300 | 3.365 | V |
| | AOZ1117-5.0 | I_{OUT} = 10mA, T_{J} = 25°C, 6.5V $\leq V_{IN} \leq$ 12V | 4.900 | 5.000 | 5.100 | V |
| Line Regulation ⁽¹⁾⁽²⁾ | All | $V_{IN} = V_{OUT} + 1.5 V \sim 7 V$, $I_O = 10 mA$, $T_J = 25 °C$ | | 0.1 | 0.3 | % |
| | | V _{IN} = V _{OUT} +1.5V~12V, I _O = 10mA, T _J = 25°C | | 0.1 | 0.5 | % |
| Load Regulation ⁽¹⁾⁽²⁾ | AOZ1117-ADJ | $V_{IN} = 3V$, $Vadj = 0,10mA < I_O < 1A$, $T_J = 25^{\circ}C$ | | | 1 | % |
| | AOZ1117-1.5 | $V_{IN} = 3V, 10mA < I_O < 1A, T_J = 25^{\circ}C$ | | 12 | 15 | mV |
| | AOZ1117-1.8 | $V_{IN} = 3.3V, 10mA < I_O < 1A, T_J = 25^{\circ}C$ | | 15 | 18 | mV |
| | AOZ1117-2.5 | $V_{IN} = 4V, 10mA < I_O < 1A, T_J = 25^{\circ}C$ | | 20 | 25 | mV |
| | AOZ1117-3.3 | $V_{IN} = 5V, \ 10mA \leq I_{OUT} \leq 1A, \ \ T_J = 25^\circ C$ | | 26 | 33 | mV |
| | AOZ1117-5.0 | V_{IN} = 6.5V, 10mA \leq I _{OUT} \leq 1A, T _J = 25°C | | 40 | 50 | mV |
| Dropout Voltage (V _{IN} –V _{OUT}) | All | I_{OUT} = 1A, ΔV_{OUT} = 1% V_{OUT} | | 1.3 | 1.4 | V |
| Current Limit | All | $V_{IN} - V_{OUT} = 3V$ | 1.1 | | | Α |
| Minimum Load Current | All | $0^{\circ}C \leq T_{j} \leq 125^{\circ}C$ | | 5 | 10 | mA |
| Ripple Rejection | All | $V_{IN} = V_{OUT} + 3V$, f = 120Hz, $C_{OUT} = 25\mu F$ Tantalum | | 60 | 70 | dB |
| Temperature Stability | All | I _O = 10mA | | 0.5 | | % |
| Thermal Resistance (θ_{JA}) | All | Junction-to-Ambient (No heat sink; no air flow) | | 92 | | °C/W |
| | | Junction-to-Ambient ⁽⁴⁾ | | 55 | | |
| Thermal Resistance (θ_{JC}) | All | Junction-to-Case | | 10 | | °C/W |

Notes:

1. See thermal regulation specifications for changes in output voltage due to heating effects. Line and load regulation are measured at a constant junction temperature by low duty cycle pulse testing. Load regulation is measured at the output lead = 1/18" from the package.

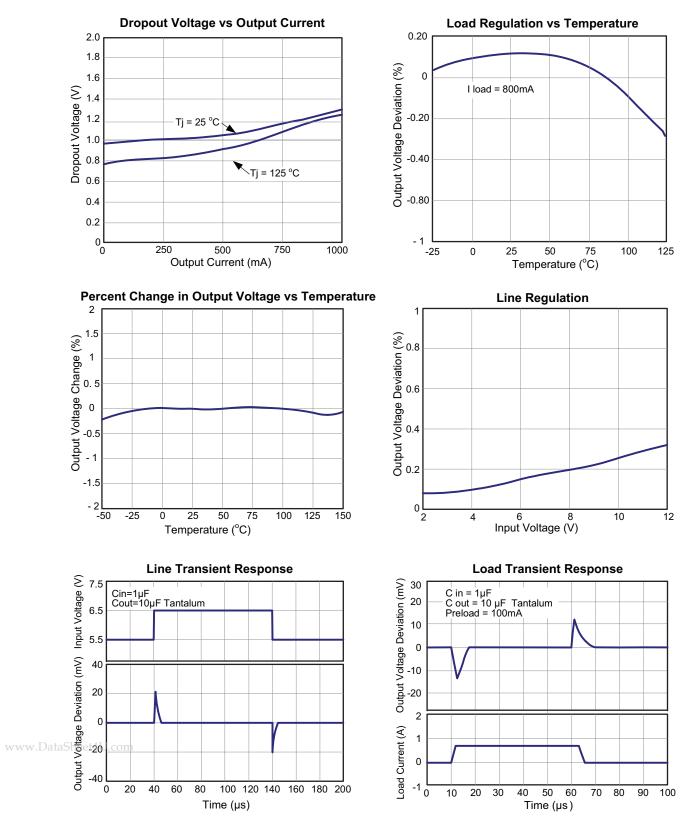
2. Line and load regulation are guaranteed up to the maximum power dissipation of 15W. Power dissipation is determined by the difference between input and output differential and the output current. Guaranteed maximum power dissipation will not be available over the full input/output range.

3. Quiescent current is defined as the minimum output current required in maintaining regulation. At 12V input/output differential the device is guaranteed to regulate if the output current is greater than 10mA.

4. Output is connected to the multi-layer PCB cupper area 10mm x 10mm separately. If you need large PD or lower Tc & Tj, please connect to the large copper area > 10mm x 10mm.

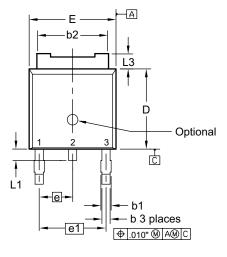


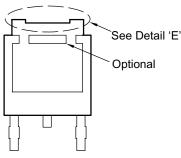
Typical Performance Characteristics

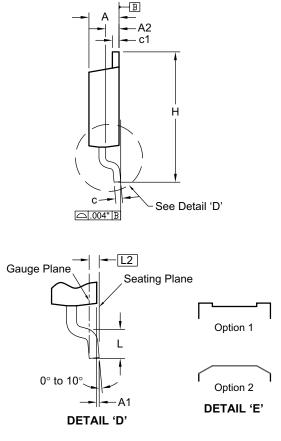




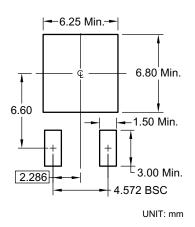
Package Dimensions, TO252-3L







RECOMMENDED LAND PATTERN



Dimensions in millimeters

Dimensions in inches

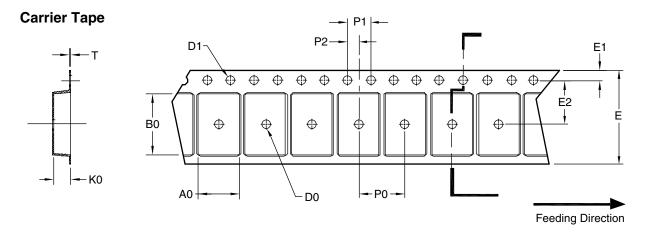
| Symbols | Min. Nom. Max. | | | | Symbols | Min. | Nom. | Max. |
|---------|----------------|--------|-------|----|---------|-----------|-------|----------------|
| А | 2.184 | 2.286 | 2.388 | | А | 0.086 | 0.090 | 0.094 |
| A1 | 0.000 | — | 0.127 | A1 | 0.000 | — | 0.005 | |
| A2 | 0.889 | | 1.143 | | A2 | 0.035 | — | 0.045 |
| b | 0.635 | 0.762 | 0.889 | ĺ | b | 0.025 | 0.030 | 0.035 |
| b1 | 0.762 | _ | 1.143 | | b1 | 0.030 | _ | 0.045 |
| b2 | 4.953 | | 5.461 | | b2 | 0.195 | _ | 0.215 |
| С | 0.450 | 0.508 | 0.610 | | С | 0.018 | 0.020 | 0.024 |
| c1 | 0.450 | | 0.610 | | c1 | 0.018 | _ | 0.024 |
| D | 5.969 | 6.096 | 6.223 | | D | 0.235 | 0.240 | 0.245 0.265 |
| Е | 6.350 | 6.604 | 6.731 | | Е | 0.250 | 0.260 | |
| е | 2.286 BSC | | | | е | 0.090 BSC | | |
| e1 | 4.572 BSC | | | | e1 | 0.180 BSC | | |
| Н | 9.398 | 10.414 | | Н | 0.370 | _ | 0.410 | |
| L | 1.270 | | 2.032 | | L | 0.050 | | 0.080 |
| L1 | 0.635 | | 1.016 | | L1 | 0.025 | | 0.040 |
| L2 | 0.508 BSC | | | | L2 | 0.020 BSC | | |
| L3 | 0.889 | | 1.270 | ĺ | L3 | 0.035 | — | 0.050 |

www.DataSheet4U.com

Notes:

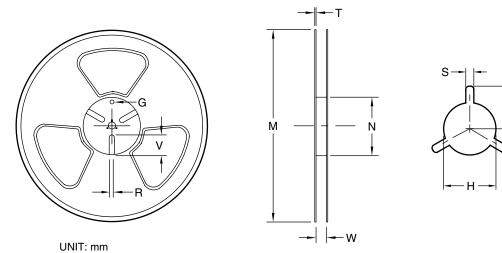
- 1. Package body sizes exclude mold flash and gate burrs. Mold flash should be less than 6 mils.
- 2. Dimension L is measured in gauge plane.
- 3. Tolerance 0.10mm unless otherwise specified.
- 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.
- 5. Refer to JEDEC TO-252(AA).

Tape and Reel Dimensions, TO252-3L

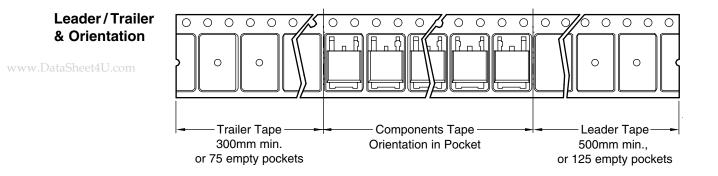


| Package A0 B0 K0 D0 D1 E E1 E2 P0 P1 P2 T TO-252 (DPAK) 6.90 10.50 2.70 1.50 1.50 16.00 1.75 7.50 8.00 4.00 2.00 0.30 (16mm) ±0.10 <t< th=""><th></th><th>UNIT: mm</th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th></t<> | | UNIT: mm | | | | | | | | | | | | |
|--|---|-------------------------|----|----|----|----|----|---|----|----|----|----|----|---------------|
| | | Package | A0 | B0 | К0 | D0 | D1 | E | E1 | E2 | P0 | P1 | P2 | Т |
| | ĺ | TO-252 (DPAK) (16mm) | | | - | | | | - | | | | | 0.30 ±0.05 |

Reel



| Tape Size | Reel Size | М | Ν | W | Т | Н | К | S | G | R | v |
|-----------|-----------|-----------------|----------------|----------------|------|-----------------|-------|--------------|---|---|---|
| 16mm | ø330 | ø330.00 ±0.5 | ø99.50 ±1.0 | 17.50 ±0.50 | 2.30 | ø13.50 +0.10 | 10.60 | 2.5 ±0.10 | | | |

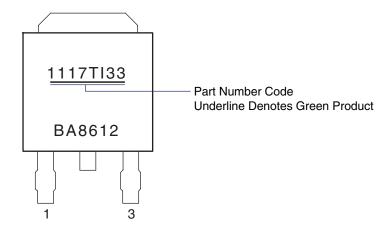


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Part Marking



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